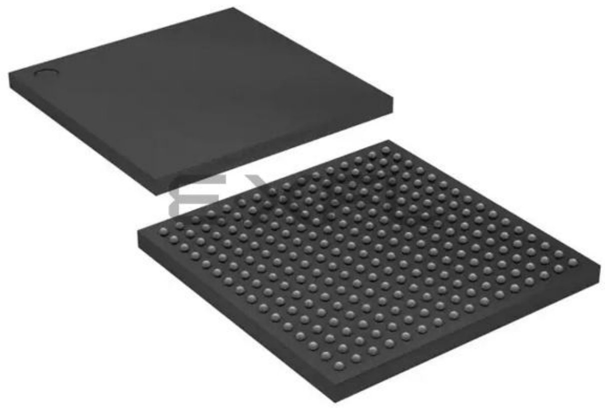


Welcome to E-XFL.COM

Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Active
Number of LABs/CLBs	392
Number of Logic Elements/Cells	6272
Total RAM Bits	276480
Number of I/O	179
Number of Gates	-
Voltage - Supply	1.15V ~ 1.25V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	256-LBGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep4ce6f17c6

2. Logic Elements and Logic Array Blocks in Cyclone IV Devices

CYIV-51002-1.0

This chapter contains feature definitions for logic elements (LEs) and logic array blocks (LABs). Details are provided on how LEs work, how LABs contain groups of LEs, and how LABs interface with the other blocks in Cyclone® IV devices.

Logic Elements

Logic elements (LEs) are the smallest units of logic in the Cyclone IV device architecture. LEs are compact and provide advanced features with efficient logic usage. Each LE has the following features:

- A four-input look-up table (LUT), which can implement any function of four variables
- A programmable register
- A carry chain connection
- A register chain connection
- The ability to drive the following interconnects:
  - Local
  - Row
  - Column
  - Register chain
  - Direct link
- Register packing support
- Register feedback support

Table 4–2 lists the sign of the multiplication results for the various operand sign representations. The results of the multiplication are signed if any one of the operands is a signed value.

Table 4–2. Multiplier Sign Representation

Data A		Data B		Result
signa Value	**Logic Level**	**signb Value**	**Logic Level**	
Unsigned	Low	Unsigned	Low	Unsigned
Unsigned	Low	Signed	High	Signed
Signed	High	Unsigned	Low	Signed
Signed	High	Signed	High	Signed

Each embedded multiplier block has only one `signa` and one `signb` signal to control the sign representation of the input data to the block. If the embedded multiplier block has two 9 × 9 multipliers, the `Data A` input of both multipliers share the same `signa` signal, and the `Data B` input of both multipliers share the same `signb` signal. You can dynamically change the `signa` and `signb` signals to modify the sign representation of the input operands at run time. You can send the `signa` and `signb` signals through a dedicated input register. The multiplier offers full precision, regardless of the sign representation.

☞ When the `signa` and `signb` signals are unused, the Quartus II software sets the multiplier to perform unsigned multiplication by default.

Output Registers

You can register the embedded multiplier output with output registers in either 18- or 36-bit sections, depending on the operational mode of the multiplier. The following control signals are available for each output register in the embedded multiplier:

- clock
- clock enable
- asynchronous clear

All input and output registers in a single embedded multiplier are fed by the same clock, clock enable, and asynchronous clear signals.

Operational Modes

You can use an embedded multiplier block in one of two operational modes, depending on the application needs:

- One 18 × 18 multiplier
- Up to two 9 × 9 independent multipliers

☞ You can also use embedded multipliers of Cyclone IV devices to implement multiplier adder and multiplier accumulator functions, in which the multiplier portion of the function is implemented with embedded multipliers, and the adder or accumulator function is implemented in logic elements (LEs).

If you do not use dedicated clock pins to feed the GCLKs, you can use them as general-purpose input pins to feed the logic array. However, when using them as general-purpose input pins, they do not have support for an I/O register and must use LE-based registers in place of an I/O register.

For more information about how to connect the clock and PLL pins, refer to the *Cyclone IV Device Family Pin Connection Guidelines*.

Clock Control Block

The clock control block drives the GCLKs. Clock control blocks are located on each side of the device, close to the dedicated clock input pins. GCLKs are optimized for minimum clock skew and delay.

Table 5–4 lists the sources that can feed the clock control block, which in turn feeds the GCLKs.

Table 5–4. Clock Control Block Inputs

Input	Description
Dedicated clock inputs	Dedicated clock input pins can drive clocks or global signals, such as synchronous and asynchronous clears, presets, or clock enables onto given GCLKs.
Dual-purpose clock (`DPCLK` and `CDPCLK`) I/O input	`DPCLK` and `CDPCLK` I/O pins are bidirectional dual function pins that are used for high fan-out control signals, such as protocol signals, `TRDY` and `IRDY` signals for PCI, via the GCLK. Clock control blocks that have inputs driven by dual-purpose clock I/O pins are not able to drive PLL inputs.
PLL outputs	PLL counter outputs can drive the GCLK.
Internal logic	You can drive the GCLK through logic array routing to enable internal logic elements (LEs) to drive a high fan-out, low-skew signal path. Clock control blocks that have inputs driven by internal logic are not able to drive PLL inputs.

In Cyclone IV devices, dedicated clock input pins, PLL counter outputs, dual-purpose clock I/O inputs, and internal logic can all feed the clock control block for each GCLK. The output from the clock control block in turn feeds the corresponding GCLK. The GCLK can drive the PLL input if the clock control block inputs are outputs of another PLL or dedicated clock input pins. There are five or six clock control blocks on each side of the device periphery—depending on device density; providing up to 30 clock control blocks in each Cyclone IV GX device. The maximum number of clock control blocks per Cyclone IV E device is 20. For the clock control block locations, refer to Figure 5–2 on page 5–12, Figure 5–3 on page 5–13, and Figure 5–4 on page 5–14.

The clock control blocks on the left side of the Cyclone IV GX device do not support any clock inputs.

The control block has two functions:

- Dynamic GCLK clock source selection (not applicable for `DPCLK`, `CDPCLK`, and internal logic input)
- GCLK network power down (dynamic enable and disable)

Table 5–12. Dynamic Phase Shifting Control Signals (Part 2 of 2)

Signal Name	Description	Source	Destination
`scanclk`	Free running clock from core used in combination with `phasestep` to enable or disable dynamic phase shifting. Shared with `scanclk` for dynamic reconfiguration.	GCLK or I/O pins	PLL reconfiguration circuit
`phasedone`	When asserted, it indicates to core logic that the phase adjustment is complete and PLL is ready to act on a possible second adjustment pulse. Asserts based on internal PLL timing. De-asserts on the rising edge of `scanclk`.	PLL reconfiguration circuit	Logic array or I/O pins

Table 5–13 lists the PLL counter selection based on the corresponding `PHASECOUNTERSELECT` setting.

Table 5–13. Phase Counter Select Mapping

phasecounterselect			Selects
[2]	[1]	[0]	
0	0	0	All Output Counters
0	0	1	M Counter
0	1	0	C0 Counter
0	1	1	C1 Counter
1	0	0	C2 Counter
1	0	1	C3 Counter
1	1	0	C4 Counter

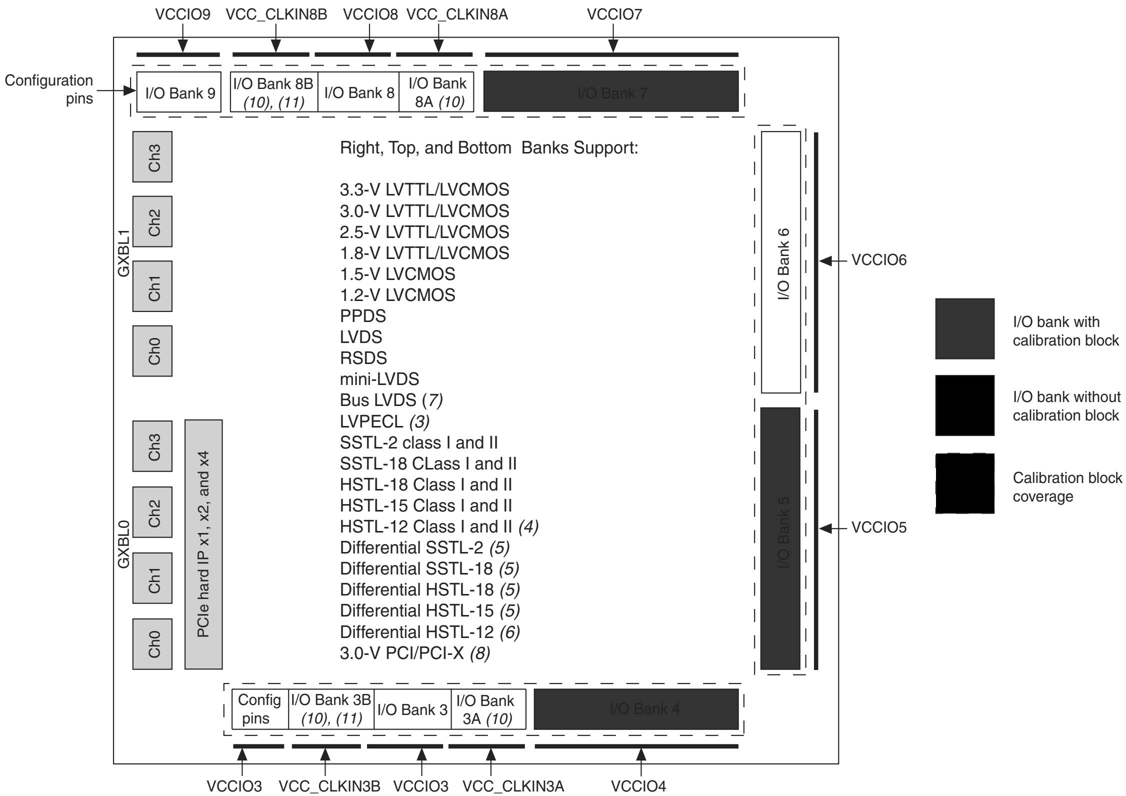
To perform one dynamic phase-shift, follow these steps:

1. Set `PHASEUPDOWN` and `PHASECOUNTERSELECT` as required.
2. Assert `PHASESTEP` for at least two `SCANCLK` cycles. Each `PHASESTEP` pulse allows one phase shift.
3. Deassert `PHASESTEP` after `PHASEDONE` goes low.
4. Wait for `PHASEDONE` to go high.
5. Repeat steps 1 through 4 as many times as required to perform multiple phase-shifts.

`PHASEUPDOWN` and `PHASECOUNTERSELECT` signals are synchronous to `SCANCLK` and must meet the t_{su} and t_h requirements with respect to the `SCANCLK` edges.

☞ You can repeat dynamic phase-shifting indefinitely. For example, in a design where the VCO frequency is set to 1,000 MHz and the output clock frequency is set to 100 MHz, performing 40 dynamic phase shifts (each one yields 125 ps phase shift) results in shifting the output clock by 180°, in other words, a phase shift of 5 ns.

Figure 6–11. Cyclone IV GX I/O Banks for EP4CGX50, EP4CGX75, EP4CGX110, and EP4CGX150 *(1), (2), (9)*



Notes to Figure 6–11:

(1) This is a top view of the silicon die. For exact pin locations, refer to the pin list and the Quartus II software.

(2) True differential (PPDS, LVDS, mini-LVDS, and RSDS I/O standards) outputs are supported in row I/O banks 5 and 6 only. External resistors are needed for the differential outputs in column I/O banks.

(3) The LVPECL I/O standard is only supported on clock input pins. This I/O standard is not supported on output pins.

(4) The HSTL-12 Class II is supported in column I/O banks 4, 7, and 8.

(5) The differential SSTL-18 and SSTL-2, differential HSTL-18, and HSTL-15 I/O standards are supported only on clock input pins and phase-locked loops (PLLs) output clock pins. PLL output clock pins do not support Class II interface type of differential SSTL-18, HSTL-18, HSTL-15, and HSTL-12 I/O standards.

(6) The differential HSTL-12 I/O standard is only supported on clock input pins and PLL output clock pins. Differential HSTL-12 Class II is supported only in column I/O banks 4, 7, and 8.

(7) BLVDS output uses two single-ended outputs with the second output programmed as inverted. BLVDS input uses the LVDS input buffer.

(8) The PCI-X I/O standard does not meet the IV curve requirement at the linear region.

(9) The OCT block is located in the shaded banks 4, 5, and 7.

(10) The dedicated clock input I/O banks 3A, 3B, 8A, and 8B can be used either for HSSI input reference clock pins or clock input pins.

(11) Single-ended clock input support is available for dedicated clock input I/O banks 3B and 8B.

RSDS, Mini-LVDS, and PPDS I/O Standard Support in Cyclone IV Devices

The RSDS, mini-LVDS, and PPDS I/O standards are used in chip-to-chip applications between the timing controller and the column drivers on the display panels such as LCD monitor panels and LCD televisions. Cyclone IV devices meet the National Semiconductor Corporation RSDS Interface Specification, Texas Instruments mini-LVDS Interface Specification, and National Semiconductor Corporation PPDS Interface Specification to support RSDS, mini-LVDS and PPDS output standards, respectively.

For Cyclone IV devices RSDS, mini-LVDS, and PPDS output electrical specifications, refer to the *Cyclone IV Device Datasheet* chapter.

For more information about the RSDS I/O standard, refer to the RSDS specification from the National Semiconductor website (www.national.com).

Designing with RSDS, Mini-LVDS, and PPDS

Cyclone IV I/O banks support RSDS, mini-LVDS, and PPDS output standards. The right I/O banks support true RSDS, mini-LVDS, and PPDS transmitters. On the top and bottom I/O banks, RSDS, mini-LVDS, and PPDS transmitters are supported using two single-ended output buffers with external resistors. The two single-ended output buffers are programmed to have opposite polarity.

Figure 6–15 shows an RSDS, mini-LVDS, or PPDS interface with a true output buffer.

Figure 6–15. Cyclone IV Devices RSDS, Mini-LVDS, or PPDS Interface with True Output Buffer on the Right I/O Banks

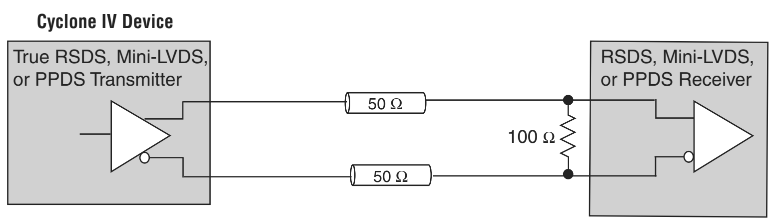
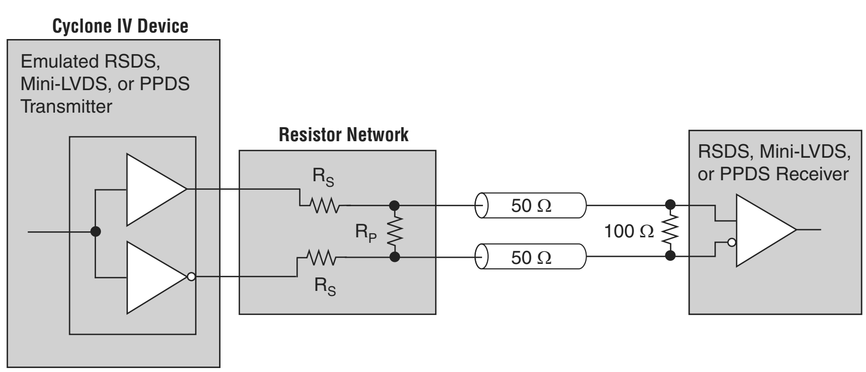


Figure 6–16 shows an RSDS, mini-LVDS, or PPDS interface with two single-ended output buffers and external resistors.

Figure 6–16. RSDS, Mini-LVDS, or PPDS Interface with External Resistor Network on the Top and Bottom I/O Banks *(1)*



During device configuration, Cyclone IV E devices read configuration data using the parallel interface and configure their SRAM cells. This scheme is referred to as the AP configuration scheme because the device controls the configuration interface. This scheme contrasts with the FPP configuration scheme, where an external host controls the interface.

AP Configuration Supported Flash Memories

The AP configuration controller in Cyclone IV E devices is designed to interface with two industry-standard flash families—the Micron P30 Parallel NOR flash family and the Micron P33 Parallel NOR flash family. Unlike serial configuration devices, both of the flash families supported in AP configuration scheme are designed to interface with microprocessors. By configuring from an industry standard microprocessor flash which allows access to the flash after entering user mode, the AP configuration scheme allows you to combine configuration data and user data (microprocessor boot code) on the same flash memory.

The Micron P30 flash family and the P33 flash family support a continuous synchronous burst read mode at 40 MHz `DCLK` frequency for reading data from the flash. Additionally, the Micron P30 and P33 flash families have identical pin-out and adopt similar protocols for data access.

☞ Cyclone IV E devices use a 40-MHz oscillator for the AP configuration scheme. The oscillator is the same oscillator used in the Cyclone IV E AS configuration scheme.

Table 8–10 lists the supported families of the commodity parallel flash for the AP configuration scheme.

Table 8–10. Supported Commodity Flash for AP Configuration Scheme for Cyclone IV E Devices (1)

Flash Memory Density	Micron P30 Flash Family (2)	Micron P33 Flash Family (3)
64 Mbit	✓	✓
128 Mbit	✓	✓
256 Mbit	✓	✓

Notes to Table 8–10:

(1) The AP configuration scheme only supports flash memory speed grades of 40 MHz and above.

(2) 3.3- , 3.0-, 2.5-, and 1.8-V I/O options are supported for the Micron P30 flash family.

(3) 3.3-, 3.0- and 2.5-V I/O options are supported for the Micron P33 flash family.

Configuring Cyclone IV E devices from the Micron P30 and P33 family 512-Mbit flash memory is possible, but you must properly drive the extra address and `FLASH_nCE` pins as required by these flash memories.

To check for supported speed grades and package options, refer to the respective flash datasheets.

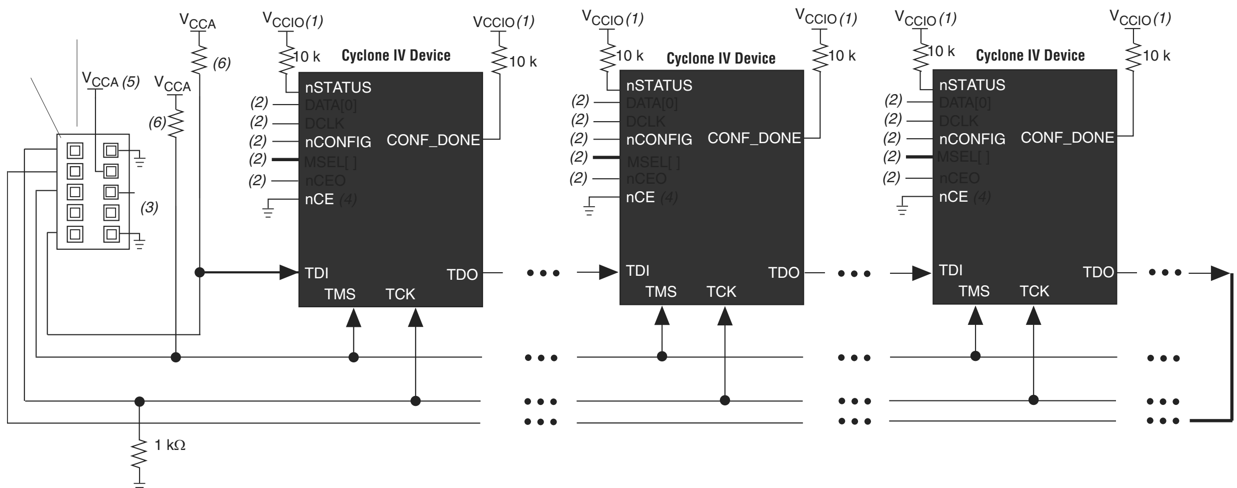
The AP configuration scheme in Cyclone IV E devices supports flash speed grades of 40 MHz and above. However, AP configuration for all these speed grades must be capped at 40 MHz. The advantage of faster speed grades is realized when your design in the Cyclone IV E devices accesses flash memory in user mode.

When programming a JTAG device chain, one JTAG-compatible header is connected to several devices. The number of devices in the JTAG chain is limited only by the drive capability of the download cable. When four or more devices are connected in a JTAG chain, Altera recommends buffering the `TCK`, `TDI`, and `TMS` pins with an on-board buffer.

JTAG-chain device programming is ideal when the system contains multiple devices, or when testing your system with JTAG BST circuitry. Figure 8–25 and Figure 8–26 show multi-device JTAG configuration.

For devices using 2.5-, 3.0-, and 3.3-V V_{CCIO} supply, you must refer to Figure 8–25. All I/O inputs must maintain a maximum AC voltage of 4.1 V because JTAG pins do not have the internal PCI clamping diodes to prevent voltage overshoot when using 2.5-, 3.0-, and 3.3- V V_{CCIO} supply. You must power up the V_{CC} of the download cable with a 2.5-V V_{CCA} supply. For device using V_{CCIO} of 1.2, 1.5 V, and 1.8 V, refer to Figure 8–26. You can power up the V_{CC} of the download cable with the supply from V_{CCIO}.

Figure 8–25. JTAG Configuration of Multiple Devices Using a Download Cable (2.5, 3.0, and 3.3-V V_{CCIO} Powering the JTAG Pins)



Notes to Figure 8–25:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Connect the `nCONFIG` and `MSEL` pins to support a non-JTAG configuration scheme. If you only use a JTAG configuration, connect the `nCONFIG` pin to logic-high and the `MSEL` pins to GND. In addition, pull `DCLK` and `DATA[0]` to either high or low, whichever is convenient on your board.

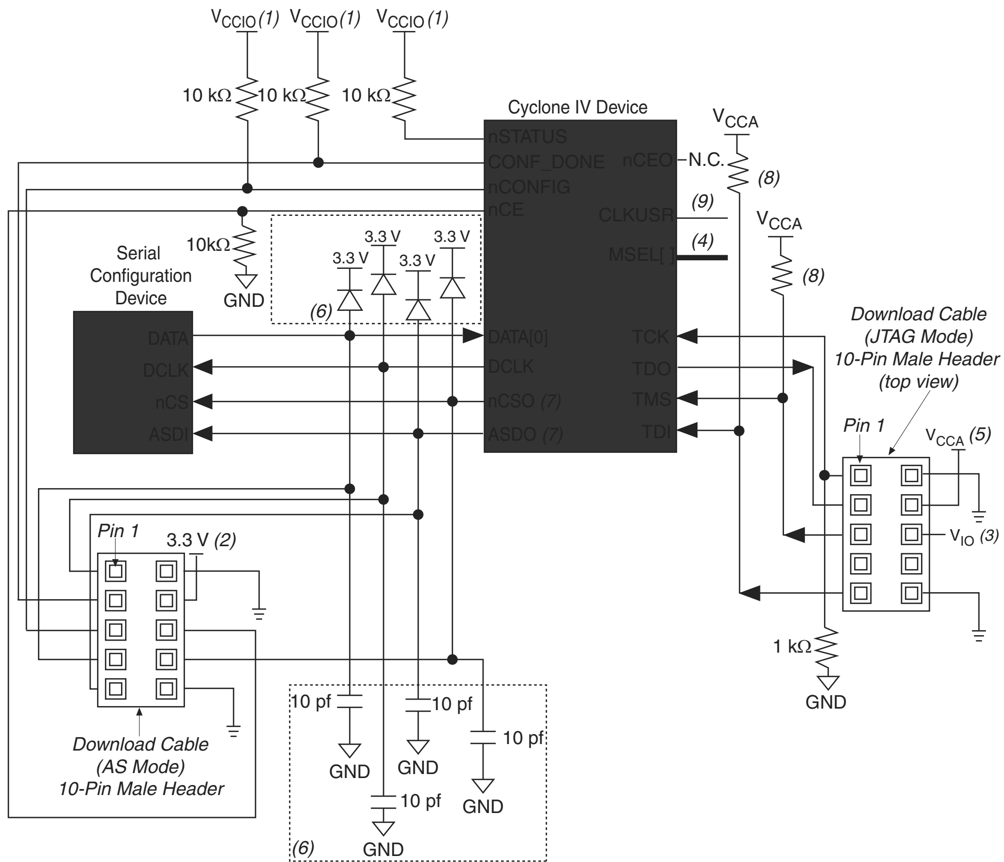
(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver. V_{IO} must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. In the ByteBlasterMV cable, this pin is a no connect. In the USB-Blaster and ByteBlaster II cables, this pin is connected to `nCE` when it is used for AS programming, otherwise it is a no connect.

(4) You must connect the `nCE` pin to GND or driven low for successful JTAG configuration.

(5) Power up the V_{CC} of the ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V supply from V_{CCA}. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(6) Resistor value can vary from 1 kΩ to 10 kΩ.

Figure 8–28. Combining JTAG and AS Configuration Schemes



Notes to Figure 8–28:

(1) Connect these pull-up resistors to the V_{CCIO} supply of the bank in which the pin resides.

(2) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, or USB-Blaster cable with the 3.3-V supply.

(3) Pin 6 of the header is a V_{IO} reference voltage for the MasterBlaster output driver.The V_{IO} must match the V_{CCA} of the device. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*. When using the ByteBlasterMV download cable, this pin is a no connect. When using the USB-Blaster and ByteBlaster II cables, this pin is connected to `nCE` when it is used for AS programming, otherwise it is a no connect.

(4) The `MSEL` pin settings vary for different configuration voltage standards and POR time. To connect `MSEL` for AS configuration schemes, refer to Table 8–3 on page 8–8, Table 8–4 on page 8–8, and Table 8–5 on page 8–9. Connect the `MSEL` pins directly to V_{CCA} or GND.

(5) Power up the V_{CC} of the EthernetBlaster, ByteBlaster II, USB-Blaster, or ByteBlasterMV cable with a 2.5-V V_{CCA} supply. Third-party programmers must switch to 2.5 V. Pin 4 of the header is a V_{CC} power supply for the MasterBlaster cable. The MasterBlaster cable can receive power from either 5.0- or 3.3-V circuit boards, DC power supply, or 5.0 V from the USB cable. For this value, refer to the *MasterBlaster Serial/USB Communications Cable User Guide*.

(6) You must place the diodes and capacitors as close as possible to the Cyclone IV device. Altera recommends using the Schottky diode, which has a relatively lower forward diode voltage (VF) than the switching and Zener diodes, for effective voltage clamping.

(7) These pins are dual-purpose I/O pins. The `nCSO` pin functions as `FLASH_nCE` pin in AP mode. The `ASDO` pin functions as `DATA[1]` pin in AP and FPP modes.

(8) Resistor value can vary from 1 kΩ to 10 kΩ..

(9) Only Cyclone IV GX devices have an option to select `CLKUSR` (40 MHz maximum) as the external clock source for `DCLK`.

Table 9–7 lists the input and output ports that you must include in the atom.

Table 9–7. CRC Block Input and Output Ports

Port	Input/Output	Definition
<crcblock_name>	Input	Unique identifier for the CRC block, and represents any identifier name that is legal for the given description language (for example, Verilog HDL, VHDL, and AHDL). This field is required.
.clk(<*clock source*>	Input	This signal designates the clock input of this cell. All operations of this cell are with respect to the rising edge of the clock. Whether it is the loading of the data into the cell or data out of the cell, it always occurs on the rising edge. This port is required.
`.shiftnld` (<*shiftnld source*>)	Input	This signal is an input into the error detection block. If `shiftnld=1`, the data is shifted from the internal shift register to the `regout` at each rising edge of `clk`. If `shiftnld=0`, the shift register parallel loads either the pre-calculated CRC value or the update register contents, depending on the `ldsrc` port input. To do this, the `shiftnld` must be driven low for at least two clock cycles. This port is required.
`.ldsrc` (<*ldsrc source*>)	Input	This signal is an input into the error detection block. If `ldsrc=0`, the pre-computed CRC register is selected for loading into the 32-bit shift register at the rising edge of `clk` when `shiftnld=0`. If `ldsrc=1`, the signature register (result of the CRC calculation) is selected for loading into the shift register at the rising edge of `clk` when `shiftnld=0`. This port is ignored when `shiftnld=1`. This port is required.
`.crcerror` (<*crcerror indicator output*>)	Output	This signal is the output of the cell that is synchronized to the internal oscillator of the device (80-MHz internal oscillator) and not to the `clk` port. It asserts high if the error block detects that a SRAM bit has flipped and the internal CRC computation has shown a difference with respect to the pre-computed value. You must connect this signal either to an output pin or a bidirectional pin. If it is connected to an output pin, you can only monitor the `CRC_ERROR` pin (the core cannot access this output). If the `CRC_ERROR` signal is used by core logic to read error detection logic, you must connect this signal to a `BIDIR` pin. The signal is fed to the core indirectly by feeding a `BIDIR` pin that has its output enable port connected to V_{CC} (see Figure 9–3 on page 9–8).
`.regout` (<*registered output*>)	Output	This signal is the output of the error detection shift register synchronized to the `clk` port to be read by core logic. It shifts one bit at each cycle, so you should clock the `clk` signal 31 cycles to read out the 32 bits of the shift register.

Recovering from CRC Errors

The system that the Altera FPGA resides in must control device reconfiguration. After detecting an error on the `CRC_ERROR` pin, strobing the `nCONFIG` low directs the system to perform the reconfiguration at a time when it is safe for the system to reconfigure the FPGA.

When the data bit is rewritten with the correct value by reconfiguring the device, the device functions correctly.

While soft errors are uncommon in Altera devices, certain high-reliability applications might require a design to account for these errors.

PIPE Interface

The PIPE interface provides a standard interface between the PCIe-compliant PHY and MAC layer as defined by the version 2.00 of the PIPE Architecture specification for Gen1 (2.5 Gbps) signaling rate. Any core or IP implementing the PHY MAC, data link, and transaction layers that supports PIPE 2.00 can be connected to the Cyclone IV GX transceiver configured in PIPE mode. Table 1–15 lists the PIPE-specific ports available from the Cyclone IV GX transceiver configured in PIPE mode and the corresponding port names in the PIPE 2.00 specification.

Table 1–15. Transceiver-FPGA Fabric Interface Ports in PIPE Mode

Transceiver Port Name	PIPE 2.00 Port Name
`tx_datain[15..0]` *(1)*	`TxData[15..0]`
`tx_ctrlenable[1..0]` *(1)*	`TxDataK[1..0]`
`rx_dataout[15..0]` *(1)*	`RxData[15..0]`
`rx_ctrldetect[1..0]` *(1)*	`RxDataK[1..0]`
`tx_detectrxloop`	`TxDetectRx/Loopback`
`tx_forceelecidle`	`TxElecIdle`
`tx_forcedispcompliance`	`TxCompliance`
`pipe8b10binvpolarity`	`RxPolarity`
`powerdn[1..0]` *(2)*	`PowerDown[1..0]`
`pipedatavalid`	`RxValid`
`pipephydonestatus`	`PhyStatus`
`pipeelecidle`	`RxElecIdle`
`pipestatus`	`RxStatus[2..0]`

Notes to Table 1–15:

(1) When used with PCIe hard IP block, the byte SERDES is not used. In this case, the data ports are 8 bits wide and control identifier is 1 bit wide.

(2) Cyclone IV GX transceivers do not implement power saving measures in lower power states (P0s, P1, and P2), except when putting the transmitter buffer in electrical idle in the lower power states.

Receiver Detection Circuitry

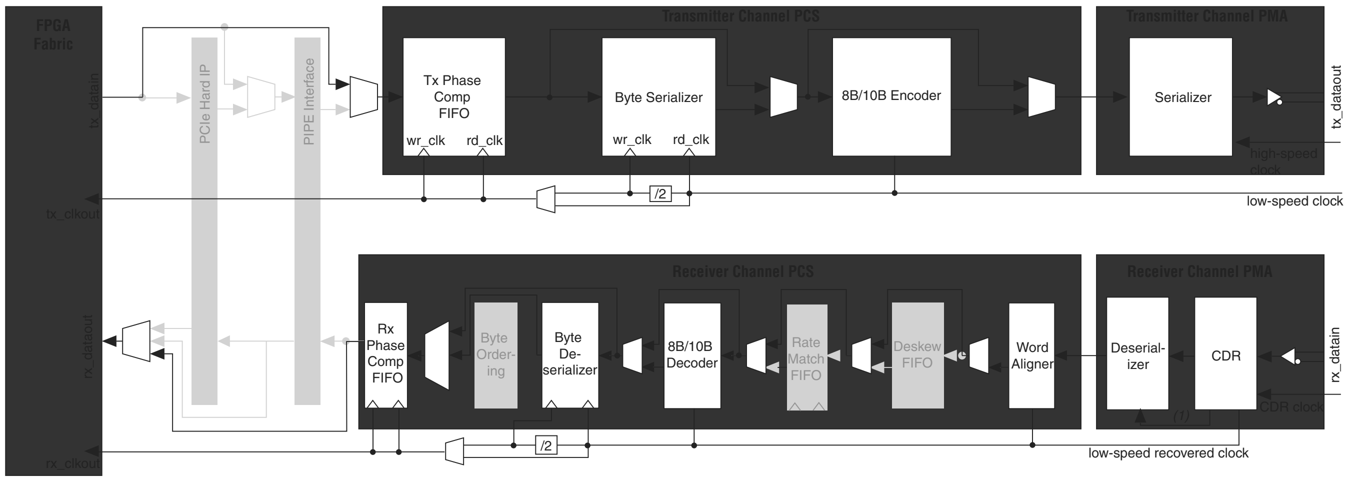
In PIPE mode, the transmitter supports receiver detection function with a built-in circuitry in the transmitter PMA. The PCIe protocol requires the transmitter to detect if a receiver is present at the far end of each lane as part of the link training and synchronization state machine sequence. This feature requires the following conditions:

- transmitter output buffer to be tri-stated
- have OCT utilization
- 125 MHz clock on the `fixedclk` port

The circuit works by sending a pulse on the common mode of the transmitter. If an active PCIe receiver is present at the far end, the time constant of the step voltage on the trace is higher compared to when the receiver is not present. The circuitry monitors the time constant of the step signal seen on the trace to decide if a receiver was detected.

Figure 1–66 shows the transceiver channel datapath and clocking when configured in deterministic latency mode.

Figure 1–66. Transceiver Channel Datapath and Clocking when Configured in Deterministic Latency Mode



Note to Figure 1–66:

(1) High-speed recovered clock.

Receive Bit-Slip Indication

The number of bits slipped in the word aligner for synchronization in manual alignment mode is provided with the `rx_bitslipboundaryselectout[4..0]` signal. For example, if one bit is slipped in word aligner to achieve synchronization, the output on `rx_bitslipboundaryselectout[4..0]` signal shows a value of 1 (5'00001). The information from this signal helps in latency calculation through the receiver as the number of bits slipped in the word aligner varies at each synchronization.

Transmit Bit-Slip Control

The transmitter datapath supports bit-slip control to delay the serial data transmission by a number of specified bits in PCS with `tx_bitslipboundaryselect[4..0]` port. With 8- or 10-bit channel width, the transmitter supports zero to nine bits of data slip. This feature helps to maintain a fixed round trip latency by compensating latency variation from word aligner when providing the appropriate values on `tx_bitslipboundaryselect[4..0]` port based on values on `rx_bitslipboundaryselectout[4..0]` signal.

PLL PFD feedback

In Deterministic Latency mode, when transmitter input reference clock frequency is the same as the low-speed clock, the PLL that clocks the transceiver supports PFD feedback. When enabled, the PLL compensates for delay uncertainty in the low-speed clock (`tx_clkout` in ×1 configuration or `coreclkout` in ×4 configuration) path relative to input reference and the transmitter datapath latency is fixed relative to the transmitter input reference clock.

SDI Mode

SDI mode provides the non-bonded (×1) transceiver channel datapath configuration for HD- and 3G-SDI protocol implementations.

Cyclone IV GX transceivers configured in SDI mode provides the serialization and deserialization functions that supports the SDI data rates as listed in Table 1–24.

Table 1–24. Supported SDI Data Rates

SMPTE Standard (1)	Configuration	Data Rate (Mbps)	FPGA Fabric-to-Transceiver Width	Byte SERDES Usage
292M	High definition (HD)	1483.5	20-bit	Used
			10-bit	Not used
		1485	20-bit	Used
			10-bit	Not used
424M	Third-generation (3G)	2967	20-bit	Used
		2970		

Note to Table 1–24:

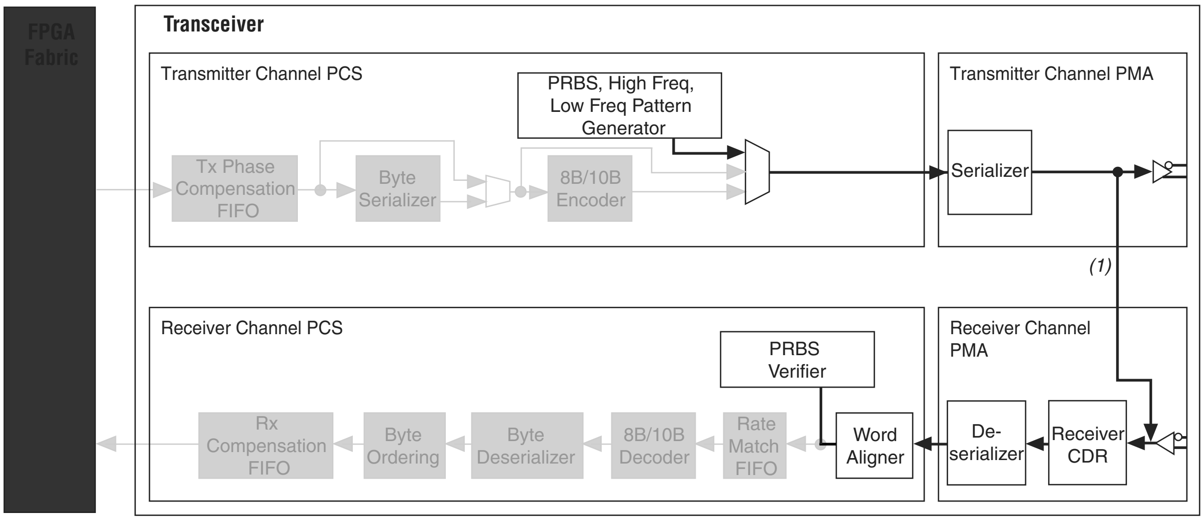
(1) Society of Motion Picture and Television Engineers (SMPTE).

☞ SDI functions such as scrambling/de-scrambling, framing, and cyclic redundancy check (CRC) must be implemented in the user logic.

PRBS

Figure 1–74 shows the datapath for the PRBS, high and low frequency pattern test modes. The pattern generator is located in TX PCS before the serializer, and PRBS pattern verifier located in RX PCS after the word aligner.

Figure 1–74. PRBS Pattern Test Mode Datapath



Note to Figure 1–74:

(1) Serial loopback path is optional and can be enabled for the PRBS verifier to check the PRBS pattern

Table 1–25 lists the supported PRBS, high and low frequency patterns, and corresponding channel settings. The PRBS pattern repeats after completing an iteration. The number of bits a PRBS X pattern sends before repeating the pattern is $2^{(X-1)}$ bits.

Table 1–25. PRBS, High and Low Frequency Patterns, and Channel Settings (Part 1 of 2)

Patterns	Polynomial	8-bit Channel Width				10-bit Channel Width			
		Channel Width of 8 bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages	Channel Width of 10-bits (1)	Word Alignment Pattern	Maximum Data Rate (Gbps) for F324 and Smaller Packages	Maximum Data Rate (Gbps) for F484 and Larger Packages
PRBS 7	$X^7 + X^6 + 1$	Y	16’h3040	2.0	2.5	N	—	—	—
PRBS 8	$X^8 + X^7 + 1$	Y	16’hFF5A	2.0	2.5	N	—	—	—
PRBS 10	$X^{10} + X^7 + 1$	N	—	—	—	Y	10’h3FF	2.5	3.125
PRBS 23	$X^{23} + X^{18} + 1$	Y	16’hFFFF	2.0	2.5	N	—	—	—
High frequency (2)	1010101010	Y	—	2.0	2.5	Y	—	2.5	3.125

Table 3–2. Dynamic Reconfiguration Controller Port List (ALTGX_RECONFIG Instance) (Part 4 of 7)

Port Name	Input/ Output	Description
Analog Settings Control/Status Signals		
`tx_vodctrl[2..0]` *(1)*	Input	This is an optional transmit buffer V_{OD} control signal. It is 3 bits per transmitter channel. The number of settings varies based on the transmit buffer supply setting and the termination resistor setting on the **TX Analog** screen of the ALTGX MegaWizard Plug-In Manager. The width of this signal is fixed to 3 bits if you enable either the **Use 'logical_channel_address' port for Analog controls reconfiguration** option or the **Use same control signal for all the channels** option in the **Analog controls** screen. Otherwise, the width of this signal is 3 bits per channel. The following shows the V_{OD} values corresponding to the `tx_vodctrl` settings for 100-Ω termination. For more information, refer to the "Programmable Output Differential Voltage" section of the *Cyclone IV GX Device Datasheet* chapter. `tx_vodctrl[2:0]` — Corresponding ALTGX instance settings — Corresponding V_{OD} settings (mV) 3'b001 — 1 — 400 3'b010 — 2 — 600 3'b011 — 3 — 800 3'b111 — 4 *(2)* — 900 *(2)* 3'b100 — 5 — 1000 3'b101 — 6 — *1200* All other values => N/A

Method 3: Writing Different Control Signals for all the Transceiver Channels at the Same Time

If you disable the **Use the same control signal for all the channels** option, the PMA control ports for a write transaction are separate for each channel. If you disable this option, the width of the PMA control ports are fixed as follows:

PMA Control Ports Used in a Write Transaction

- `tx_vodctrl` is 3 bits per channel
- `tx_preemp` are 5 bits per channel
- `rx_eqdcgain` is 2 bits per channel
- `rx_eqctrl` is 4 bits per channel

For example, if you have two channels, the `tx_vodctrl` is 6 bits wide (`tx_vodctrl [2:0]` corresponds to channel 1 and `tx_vodctrl [5:3]` corresponds to channel 2).

PMA Control Ports Used in a Read Transaction

The width of the PMA control ports for a read transaction are always separate for each channel as explained in “Method 2: Writing the Same Control Signals to Control All the Transceiver Channels” on page 3–16.

Write Transaction

Because the PMA controls of all the channels are written, if you want to reconfigure a specific channel connected to the ALTGX_RECONFIG instance, set the new value at the corresponding PMA control port of the channel under consideration and retain the previously stored values in the other active channels with a read transaction prior to this write transaction.

For example, if the number of channels controlled by the ALTGX_RECONFIG instance is two, the `tx_vodctrl` signal in this case would be 6 bits wide. The `tx_vodctrl[2:0]` signal corresponds to channel 1 and the `tx_vodctrl[5:3]` signal corresponds to channel 2.

- To dynamically reconfigure the PMA controls of only channel 2 with a new value, first perform a read transaction to retrieve the existing PMA control values from `tx_vodctrl_out[5:0]`. Use the `tx_vodctrl_out[2:0]` value for `tx_vodctrl[2:0]` to write in channel 1. By doing so, channel 1 is overwritten with the same value.
- Perform a write transaction. This ensures that the new values are written only to channel 2 while channel 1 remains unchanged.

Table 1–20. Differential I/O Standard Specifications for Cyclone IV Devices *(1)* (Part 2 of 2)

I/O Standard	V_{CCIO} (V)			V_{ID} (mV)		V_{IcM} (V) *(2)*			V_{OD} (mV) *(3)*			V_{OS} (V) *(3)*		
	Min	**Typ**	**Max**	**Min**	**Max**	**Min**	**Condition**	**Max**	**Min**	**Typ**	**Max**	**Min**	**Typ**	**Max**
LVDS (Column I/Os)	2.375	2.5	2.625	100	—	0.05	$D_{MAX} \leq$ 500 Mbps	1.80	247	—	600	1.125	1.25	1.375
						0.55	500 Mbps $\leq D_{MAX} \leq$ 700 Mbps	1.80						
						1.05	D_{MAX} > 700 Mbps	1.55						
BLVDS (Row I/Os) *(4)*	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
BLVDS (Column I/Os) *(4)*	2.375	2.5	2.625	100	—	—	—	—	—	—	—	—	—	—
mini-LVDS (Row I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
mini-LVDS (Column I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	300	—	600	1.0	1.2	1.4
RSDS® (Row I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
RSDS (Column I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.5
PPDS (Row I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4
PPDS (Column I/Os) *(5)*	2.375	2.5	2.625	—	—	—	—	—	100	200	600	0.5	1.2	1.4

Notes to Table 1–20:

(1) For an explanation of terms used in Table 1–20, refer to “Glossary” on page 1–37.

(2) V_{IN} range: 0 V $\leq V_{IN} \leq$ 1.85 V.

(3) R_L range: 90 $\leq R_L \leq$ 110 Ω .

(4) There are no fixed V_{IN}, V_{OD}, and V_{OS} specifications for BLVDS. They depend on the system topology.

(5) The Mini-LVDS, RSDS, and PPDS standards are only supported at the output pins.

(6) The LVPECL I/O standard is only supported on dedicated clock input pins. This I/O standard is not supported for output pins.